TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

# 2SK2604

### **Switching Regulator Applications**

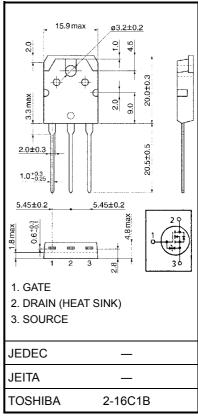
Unit: mm

• Low drain-source ON resistance  $: RDS (ON) = 1.9 \Omega (typ.)$ • High forward transfer admittance  $: |Y_{fs}| = 3.8 S (typ.)$ • Low leakage current  $: IDSS = 100 \mu A (max) (VDS = 640 V)$ 

• Enhancement-mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	800	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20k Ω)	$V_{DGR}$	800	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	15	Α	
Drain power dissipation	n (Tc = 25°C)	$P_{D}$	125	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	370	mJ	
Avalanche current		I <sub>AR</sub>	5	Α	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	12.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	inge	T <sub>stg</sub>	-55~150	°C	



Weight: 4.6 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.0	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 27 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

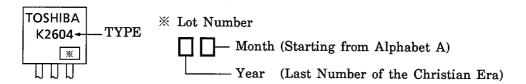
## **Electrical Characteristics (Ta = 25°C)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cur	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 640 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	800	_	_	V
Gate threshold v	roltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A,	_	1.9	2.2	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A	1.0	3.8	_	S
Input capacitanc	е	C <sub>iss</sub>			1080	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	16	_	
Output capacitance		Coss	]		105	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = \frac{10V}{0V}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{DD} = 200V$	_	40	_	- ns
	Turn-on time	t <sub>on</sub>		_	80	_	
	Fall time	t <sub>f</sub>		_	40	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	_	140	_	
Total gate charge (gate-source plus gate-drain)		Qg			34	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		16	_	nC
Gate-drain ("miller") Charge		$Q_{gd}$			18	_	

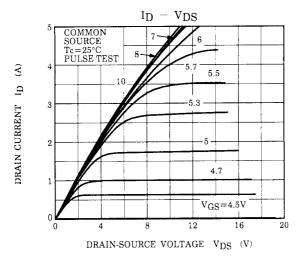
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

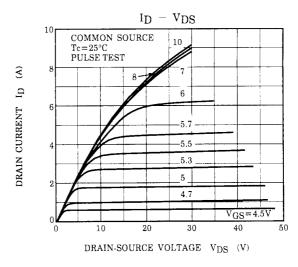
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>		_	_	5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>		_		15	Α
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_	_	-1.9	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 100 A / μs	_	1000	_	ns
Reverse recovery charge	$Q_{rr}$	TDR - 5 Λ, VGS - 5 V, αιDR / αι - 100 Α / μs	_	7.5	_	μC

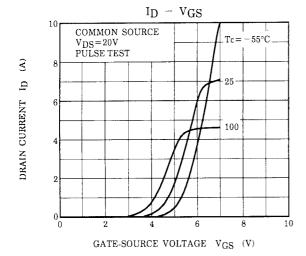
# Marking

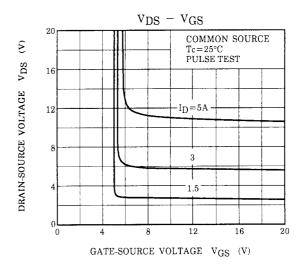


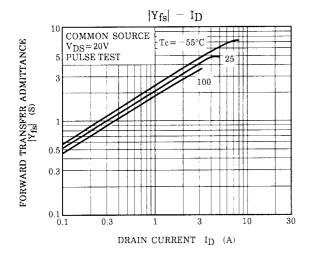
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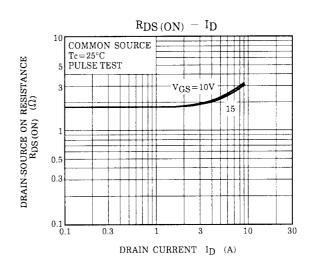




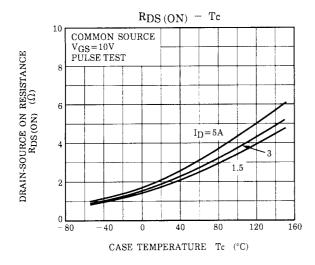


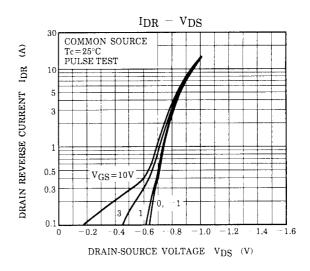


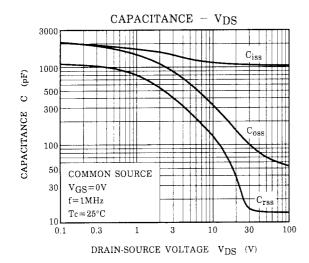


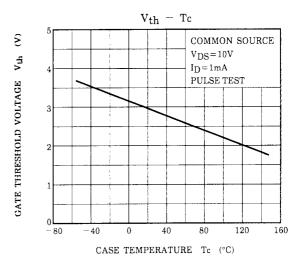


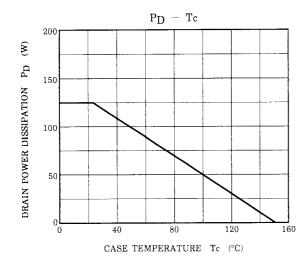
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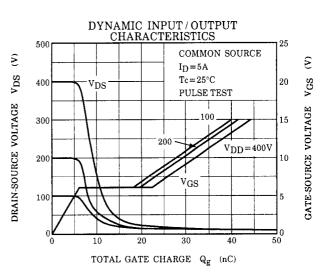




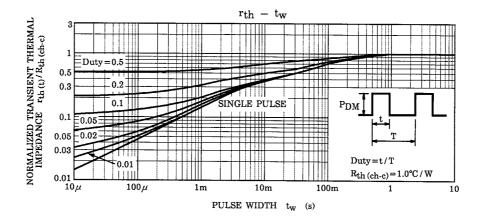


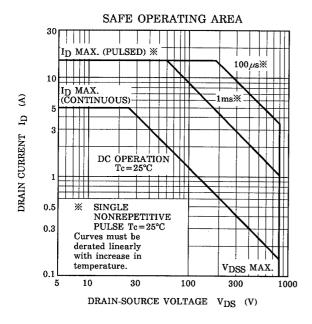


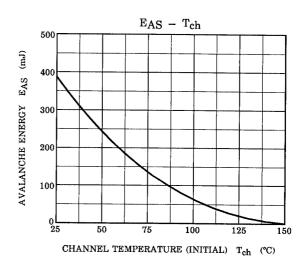


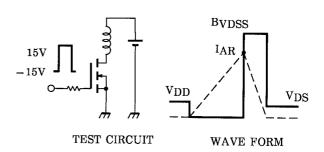


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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 27~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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